

Material Technical Data Sheet

Epoxy Resin TYPE XE200

1. Use description

Epoxy resin XE200 is an epoxy resin adhesive cured at room temperature and low temperature conditions, low heat, anti-yellowing, strong adhesion, good fluidity, natural defoaming, greenhouse curing or heat curing; dedicated to the river table, wood and Resin combined with the art table, each time can be perfused 10kg products, handicrafts, jewelry, as well as electronic potting and bonding and mold infusion and other electronic components of insulation, moisture potting, confidential cover and so on.

2. Hardening properties

	Epoxy resin XE200	Hardener XE200
Color:	Colorless and transparent	
Proportion:	1.15	0.96
Viscosity 25°C:	MAX 500CPS	100MAXCPS

3. Conditions of Use

Ratio:	A : B=100 : 33 (weight ratio)
Hardening conditions:	25°C×10H-12H 55°C×2H
Pot life:	25°C×55min

4. Use method

1. Working environment: Please keep the plastic container clean. A, B components are strictly according to the weight ratio, accurately weighed, and stir it evenly along the inner wall of the container clockwise until it is used for 3-5 minutes.

2. According to the operating time and amount of glue deployment, to avoid waste. When the temperature is lower than 15 °C, please pre-heat the A glue to 30 °C and then adjust the rubber, easy to operate (low temperature, A glue will thicken); After use must seal the lid, to avoid the product due to moisture absorption scrapped.

3. When the relative humidity is more than 85%, the surface of the cured product can easily absorb the moisture in the air to form a white mist. Therefore, when the relative humidity is more than 85%, it is not suitable for room temperature curing. It is recommended to use the heating and curing.

4. The lid must be sealed after use to avoid the product being scrapped due to moisture absorption.

5.Composition

Composition	CAS#	%by wt.
Epoxy resin	38891-59-7	64%
Benzyl alcohol	100-51-6	9%
Polyether	9046-10-0	24%
Other additions	/	3%

6.Hardened property

Hardness:	shore D	<85
Withstand voltage:	KV/mm	22
Bending strength:	MPa	28
Thermal Conductivity :	W/M*K	1.36
Heat distortion temperature :	°C	80
Water absorption :	%	<0.15
Compressive strength :	MPa	84

The above performance data is typical data measured in a laboratory environment with a temperature of 25°C and a humidity of 70%. It is for customer reference only.

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